Lattice Semiconductor Corporation - LFE2M35SE-6F672C Datasheet

Welcome to E-XFL.COM

Understanding Embedded - FPGAs (Field Programmable Gate Array)

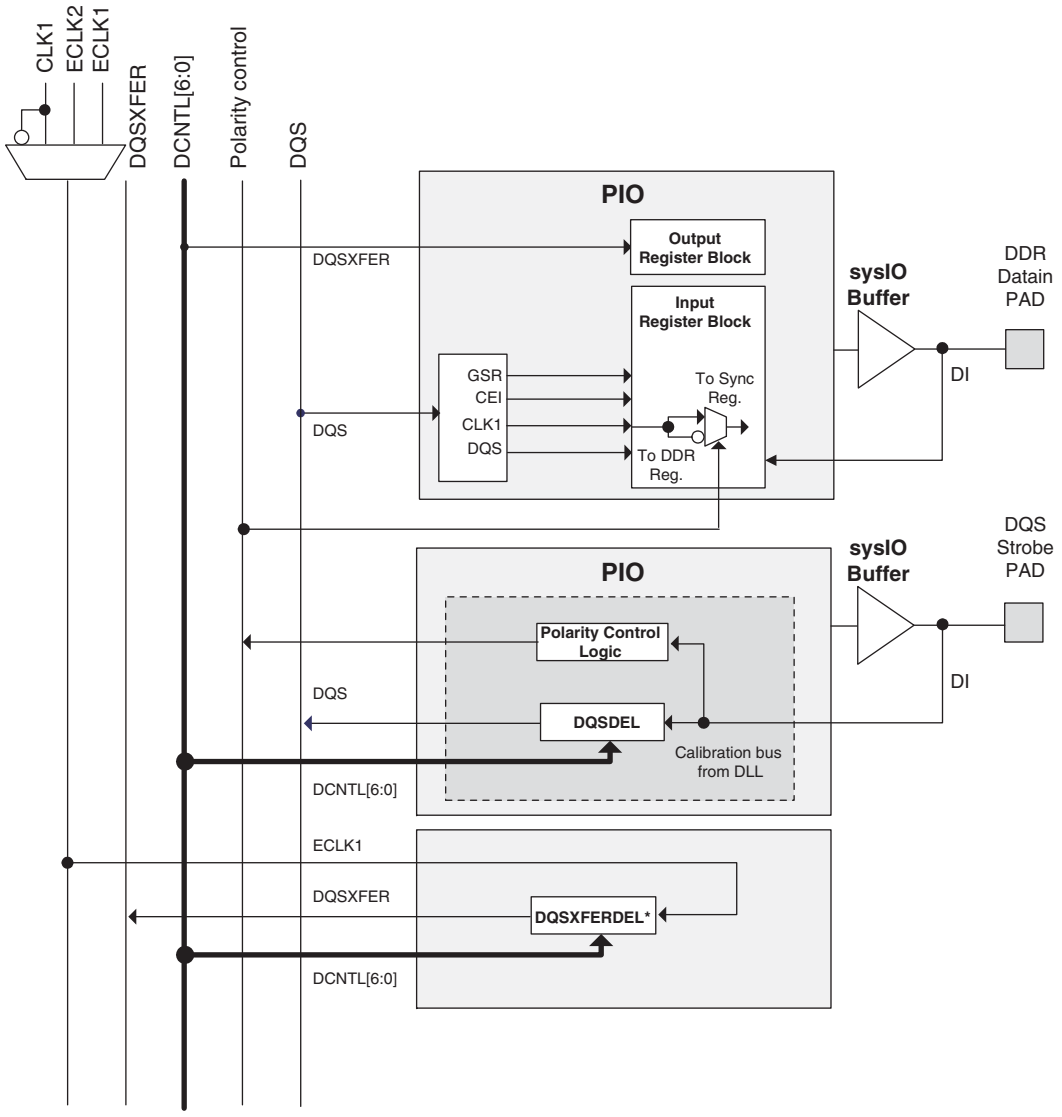
Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	4250
Number of Logic Elements/Cells	34000
Total RAM Bits	2151424
Number of I/O	410
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	672-BBGA
Supplier Device Package	672-FPBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2m35se-6f672c

Figure 2-36. DQS Local Bus



*DQSXFERDEL shifts ECLK1 by 90% and is not associated with a particular PIO.

Polarity Control Logic

In a typical DDR Memory interface design, the phase relationship between the incoming delayed DQS strobe and the internal system clock (during the READ cycle) is unknown.

The LatticeECP2/M family contains dedicated circuits to transfer data between these domains. To prevent set-up and hold violations, at the domain transfer between DQS (delayed) and the system clock, a clock polarity selector is used. This changes the edge on which the data is registered in the synchronizing registers in the input register block. This requires evaluation at the start of each READ cycle for the correct clock polarity.

Prior to the READ operation in DDR memories, DQS is in tristate (pulled by termination). The DDR memory device drives DQS low at the start of the preamble state. A dedicated circuit detects the first DQS rising edge after the preamble state. This signal is used to control the polarity of the clock to the synchronizing registers.

DQSXFER

LatticeECP2/M devices provide a DQSXFER signal to the output buffer to assist it in data transfer to DDR memories that require DQS strobe be shifted 90°. This shifted DQS strobe is generated by the DQSDEL block. The DQSXFER signal runs the span of the data bus.

sysI/O Buffer

Each I/O is associated with a flexible buffer referred to as a sysI/O buffer. These buffers are arranged around the periphery of the device in groups referred to as banks. The sysI/O buffers allow users to implement the wide variety of standards that are found in today's systems including LVCMOS, SSTL, HSTL, LVDS and LVPECL.

sysI/O Buffer Banks

LatticeECP2/M devices have nine sysI/O buffer banks: eight banks for user I/Os arranged two per side. The ninth sysI/O buffer bank (Bank 8) is located adjacent to Bank 3 and has dedicated/shared I/Os for configuration. When a shared pin is not used for configuration it is available as a user I/O. Each bank is capable of supporting multiple I/O standards. Each sysI/O bank has its own I/O supply voltage (V_{CCIO}). In addition, each bank, except Bank 8, has voltage references, V_{REF1} and V_{REF2}, which allow it to be completely independent from the others. Bank 8 shares two voltage references, V_{REF1} and V_{REF2}, with Bank 3. Figure 2-37 shows the nine banks and their associated supplies.

In LatticeECP2/M devices, single-ended output buffers and ratioed input buffers (LVTTL, LVCMOS and PCI) are powered using V_{CCIO}. LVTTL, LVCMOS33, LVCMOS25 and LVCMOS12 can also be set as fixed threshold inputs independent of V_{CCIO}.

Each bank can support up to two separate V_{REF} voltages, V_{REF1} and V_{REF2}, that set the threshold for the referenced input buffers. Some dedicated I/O pins in a bank can be configured to be a reference voltage supply pin. Each I/O is individually configurable based on the bank's supply and reference voltages.

IEEE 1149.1-Compliant Boundary Scan Testability

All LatticeECP2/M devices have boundary scan cells that are accessed through an IEEE 1149.1 compliant Test Access Port (TAP). This allows functional testing of the circuit board, on which the device is mounted, through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test data to be captured and shifted out for verification. The test access port consists of dedicated I/Os: TDI, TDO, TCK and TMS. The test access port has its own supply voltage V_{CCJ} and can operate with LVCMOS3.3, 2.5, 1.8, 1.5 and 1.2 standards.

For more details on boundary scan test, please see information regarding additional technical documentation at the end of this data sheet.

Device Configuration

All LatticeECP2/M devices contain two ports that can be used for device configuration. The Test Access Port (TAP), which supports bit-wide configuration, and the sysCONFIG port, support both byte-wide and serial configuration, including the standard SPI Flash interface. The TAP supports both the IEEE Standard 1149.1 Boundary Scan specification and the IEEE Standard 1532 In- System Configuration specification. The sysCONFIG port is a 20-pin interface with six I/Os used as dedicated pins with the remainder used as dual-use pins. See TN1108, LatticeECP2/M sysCONFIG Usage Guide for more information about using the dual-use pins as general purpose I/Os.

On power-up, the FPGA SRAM is ready to be configured using the selected sysCONFIG port. Once a configuration port is selected, it will remain active throughout that configuration cycle. The IEEE 1149.1 port can be activated any time after power-up by sending the appropriate command through the TAP port.

Enhanced Configuration Option

LatticeECP2/M devices have enhanced configuration features such as: decryption support, TransFR™ I/O and dual boot image support.

1. **Decryption Support**
   LatticeECP2/M devices provide on-chip, One Time Programmable (OTP) non-volatile key storage to support decryption of a 128-bit AES encrypted bitstream, securing designs and deterring design piracy.

2. **TransFR (Transparent Field Reconfiguration)**
   TransFR I/O (TFR) is a unique Lattice technology that allows users to update their logic in the field without interrupting system operation using a single ispVM® command. TransFR I/O allows I/O states to be frozen during device configuration. This allows the device to be field updated with a minimum of system disruption and downtime. See TN1087, Minimizing System Interruption During Configuration Using TransFR Technology, for details.

3. **Dual Boot Image Support**
   Dual boot images are supported for applications requiring reliable remote updates of configuration data for the system FPGA. After the system is running with a basic configuration, a new boot image can be downloaded remotely and stored in a separate location in the configuration storage device. Any time after the update the LatticeECP2/M can be re-booted from this new configuration file. If there is a problem, such as corrupt data during download or incorrect version number with this new boot image, the LatticeECP2/M device can revert back to the original backup configuration and try again. This all can be done without power cycling the system.

For more information about device configuration, please see the list of additional technical documentation at the end of this data sheet.

Soft Error Detect (SED) Support

LatticeECP2/M devices have dedicated logic to perform CRC checks. During configuration, the configuration data bitstream can be checked with the CRC logic block. In addition, the LatticeECP2 device can also be programmed

LatticeECP2/M Family Timing Adders[1, 2, 3] (Continued)

Over Recommended Operating Conditions

Buffer Type	Description	-7	-6	-5	Units
HSTL15_I	HSTL_15 class I 4mA drive	-0.22	-0.25	-0.27	ns
HSTL15D_I	Differential HSTL 15 class I 4mA drive	-0.22	-0.25	-0.27	ns
SSTL33_I	SSTL_3 class I	-0.12	-0.15	-0.18	ns
SSTL33_II	SSTL_3 class II	-0.20	-0.23	-0.27	ns
SSTL33D_I	Differential SSTL_3 class I	-0.12	-0.15	-0.18	ns
SSTL33D_II	Differential SSTL_3 class II	-0.20	-0.23	-0.27	ns
SSTL25_I	SSTL_2 class I 8mA drive	-0.16	-0.19	-0.22	ns
SSTL25_II	SSTL_2 class II 16mA drive	-0.19	-0.22	-0.25	ns
SSTL25D_I	Differential SSTL_2 class I 8mA drive	-0.16	-0.19	-0.22	ns
SSTL25D_II	Differential SSTL_2 class II 16mA drive	-0.19	-0.22	-0.25	ns
SSTL18_I	SSTL_1.8 class I	-0.14	-0.17	-0.20	ns
SSTL18_II	SSTL_1.8 class II 8mA drive	-0.20	-0.23	-0.25	ns
SSTL18D_I	Differential SSTL_1.8 class I	-0.14	-0.17	-0.20	ns
SSTL18D_II	Differential SSTL_1.8 class II 8mA drive	-0.20	-0.23	-0.25	ns
LVTTL33_4mA	LVTTL 4mA drive	0.52	0.60	0.68	ns
LVTTL33_8mA	LVTTL 8mA drive	0.06	0.08	0.09	ns
LVTTL33_12mA	LVTTL 12mA drive	0.04	0.04	0.05	ns
LVTTL33_16mA	LVTTL 16mA drive	0.03	0.02	0.02	ns
LVTTL33_20mA	LVTTL 20mA drive	-0.09	-0.09	-0.10	ns
LVCMOS33_4mA	LVCMOS 3.3 4mA drive, fast slew rate	0.52	0.60	0.68	ns
LVCMOS33_8mA	LVCMOS 3.3 8mA drive, fast slew rate	0.06	0.08	0.09	ns
LVCMOS33_12mA	LVCMOS 3.3 12mA drive, fast slew rate	0.04	0.04	0.05	ns
LVCMOS33_16mA	LVCMOS 3.3 16mA drive, fast slew rate	0.03	0.02	0.02	ns
LVCMOS33_20mA	LVCMOS 3.3 20mA drive, fast slew rate	-0.09	-0.09	-0.10	ns
LVCMOS25_4mA	LVCMOS 2.5 4mA drive, fast slew rate	0.41	0.47	0.53	ns
LVCMOS25_8mA	LVCMOS 2.5 8mA drive, fast slew rate	0.01	0.01	0.00	ns
LVCMOS25_12mA	LVCMOS 2.5 12mA drive, fast slew rate	0.00	0.00	0.00	ns
LVCMOS25_16mA	LVCMOS 2.5 16mA drive, fast slew rate	0.04	0.04	0.04	ns
LVCMOS25_20mA	LVCMOS 2.5 20mA drive, fast slew rate	-0.09	-0.10	-0.11	ns
LVCMOS18_4mA	LVCMOS 1.8 4mA drive, fast slew rate	0.37	0.40	0.43	ns
LVCMOS18_8mA	LVCMOS 1.8 8mA drive, fast slew rate	0.10	0.12	0.13	ns
LVCMOS18_12mA	LVCMOS 1.8 12mA drive, fast slew rate	-0.02	-0.02	-0.02	ns
LVCMOS18_16mA	LVCMOS 1.8 16mA drive, fast slew rate	-0.02	-0.03	-0.03	ns
LVCMOS15_4mA	LVCMOS 1.5 4mA drive, fast slew rate	0.29	0.31	0.32	ns
LVCMOS15_8mA	LVCMOS 1.5 8mA drive, fast slew rate	0.05	0.05	0.06	ns
LVCMOS12_2mA	LVCMOS 1.2 2mA drive, fast slew rate	0.58	0.69	0.79	ns
LVCMOS12_6mA	LVCMOS 1.2 6mA drive, fast slew rate	0.13	0.19	0.26	ns
LVCMOS33_4mA	LVCMOS 3.3 4mA drive, slow slew rate	2.17	2.44	2.71	ns
LVCMOS33_8mA	LVCMOS 3.3 8mA drive, slow slew rate	2.50	2.67	2.83	ns
LVCMOS33_12mA	LVCMOS 3.3 12mA drive, slow slew rate	1.72	1.88	2.05	ns
LVCMOS33_16mA	LVCMOS 3.3 16mA drive, slow slew rate	1.64	1.63	1.62	ns
LVCMOS33_20mA	LVCMOS 3.3 20mA drive, slow slew rate	1.33	1.36	1.39	ns

Signal Descriptions (Cont.)

Signal Name	I/O	Description
[LOC]_SQ_VCCIBm	—	Input buffer power supply, channel m (1.2V/1.5V). This pin should be left floating if the channel is unused.
[LOC]_SQ_VCCOBm	—	Output buffer power supply, channel m (1.2V/1.5V). This pin should be left floating if the channel is unused.
[LOC]_SQ_HDOUTNm	O	High-speed output, negative channel m
[LOC]_SQ_HDOUTPm	O	High-speed output, positive channel m
[LOC]_SQ_HDINNm	I	High-speed input, negative channel m
[LOC]_SQ_HDINPm	I	High-speed input, positive channel m
[LOC]_SQ_VCCTXm[4]	—	Transmitter power supply, channel m (1.2V). This pin must be tied to 1.2V even if the channel is unused.
[LOC]_SQ_VCCRXm[4]	—	Receiver power supply, channel m (1.2V). This pin must be tied to 1.2V even if the channel is unused.

1. These signals are relevant for LatticeECP2M family.
2. m defines the associated channel in the Quad.
3. These signals are defined in Quads [LOC] indicates the corner SERDES Quad is located: ULC (upper left), URC (upper right), LLC (lower left), LRC (lower right).
4. When placing switching I/Os around these critical pins that are designed to supply the device with the proper reference or supply voltage, care must be given. For more information, refer to TN1159, LatticeECP2/M Pin Assignment Recommendations.
5. There may be SPLLs that do not have dedicated I/Os.

LFE2-6E/SE and LFE2-12E/SE Logic Signal Connections: 256 fpBGA (Cont.)

LFE2-6E/SE					LFE2-12E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
R12	GND	-			GND	-		
R5	GND	-			GND	-		
T1	GND	-			GND	-		
T16	GND	-			GND	-		

* Supports true LVDS. Other differential signals must be emulated with external resistors.
** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

LFE2-20E/SE Logic Signal Connections: 256 fpBGA (Cont.)

LFE2-20E/SE					
Ball Number	Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
L11	L11	PB61B	4	BDQ60	C
T13	T13	PB62A	4	BDQ60	T
R13	R13	PB63A	4	BDQ60	T
VCCIO	VCCIO	VCCIO4	4		
T14	T14	PB62B	4	BDQ60	C
P13	P13	PB63B	4	BDQ60	C
GND	GND	GNDIO4	-		
N12	N12	PB64A	4	VREF2_4/BDQ60	T
M12	M12	PB64B	4	VREF1_4/BDQ60	C
R15	R15	CFG2	8		
N14	N14	CFG1	8		
N13	N13	PROGRAMN	8		
N15	N15	CFG0	8		
P15	P15	PR44B	8	WRITEN	C
L12	L12	INITN	8		
N16	N16	PR43B	8	CSN	C
GND	GND	GNDIO8	-		
R14	R14	CCLK	8		
P14	P14	PR44A	8	CS1N	T
M13	M13	DONE	8		
R16	R16	PR42B	8	D1	C
VCCIO	VCCIO	VCCIO8	8		
M16	M16	PR43A	8	D0/SPIFASTN	T
P16	P16	PR42A	8	D2	T
L15	L15	PR41B	8	D3	C
GND	GND	GNDIO8	-		
L14	L14	PR40A	8	D6	T
L16	L16	PR41A	8	D4	T
L10	L10	PR39B	8	D7/SPID0	C
L13	L13	PR40B	8	D5	C
VCCIO	VCCIO	VCCIO8	8		
K11	K11	PR39A	8	DI/CSSPI0N	T
K14	K14	PR38B	8	DOUT/CSON	C
K13	K13	PR38A	8	BUSY/SISPI	T
GND	GND	GNDIO8	-		
K15	K15	PR31B	3	RLM0_GPLLC_FB_A/RDQ34	C
VCCIO	VCCIO	VCCIO3	3		
K16	K16	PR31A	3	RLM0_GPLLT_FB_A/RDQ34	T
GND	GND	GNDIO3	-		
J16	J16	PR30B	3	RLM0_GPLLC_IN_A**/RDQ34	C (LVDS)*
J15	J15	PR30A	3	RLM0_GPLLT_IN_A**/RDQ34	T (LVDS)*
J14	J14	RLM0_PLLCAP	3		

LFE2-12E/SE and LFE2-20E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2-12E/12SE					LFE2-20E/20SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
J9	GND	-			GND	-		
K10	GND	-			GND	-		
K11	GND	-			GND	-		
K12	GND	-			GND	-		
K13	GND	-			GND	-		
K15	GND	-			GND	-		
K8	GND	-			GND	-		
L10	GND	-			GND	-		
L11	GND	-			GND	-		
L12	GND	-			GND	-		
L13	GND	-			GND	-		
L15	GND	-			GND	-		
L8	GND	-			GND	-		
M10	GND	-			GND	-		
M11	GND	-			GND	-		
M12	GND	-			GND	-		
M13	GND	-			GND	-		
M15	GND	-			GND	-		
M8	GND	-			GND	-		
N10	GND	-			GND	-		
N11	GND	-			GND	-		
N12	GND	-			GND	-		
N13	GND	-			GND	-		
N15	GND	-			GND	-		
N8	GND	-			GND	-		
P14	GND	-			GND	-		
P20	GND	-			GND	-		
P3	GND	-			GND	-		
P9	GND	-			GND	-		
R10	GND	-			GND	-		
R11	GND	-			GND	-		
R12	GND	-			GND	-		
R13	GND	-			GND	-		
U17	GND	-			GND	-		
U6	GND	-			GND	-		
W2	GND	-			GND	-		
W21	GND	-			GND	-		
Y14	GND	-			GND	-		
Y9	GND	-			GND	-		
H6	NC	-			NC	-		
J6	NC	-			NC	-		
H3	NC	-			NC	-		
H2	NC	-			NC	-		
H17	NC	-			NC	-		

LFE2-12E/SE and LFE2-20E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2-12E/12SE					LFE2-20E/20SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
H16	NC	-			NC	-		
H20	NC	-			NC	-		
H18	NC	-			NC	-		
K6	NC	-			NC	-		
J16	NC	-			NC	-		
N18	VCC	-			VCC	-		
N6	VCC	-			VCC	-		

* Supports true LVDS. Other differential signals must be emulated with external resistors.
** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

LFE2-35E/SE and LFE2-50E/SE Logic Signal Connections: 484 fpBGA

LFE2-35E/SE					LFE2-50E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
E4	PL2A	7	VREF2_7/LDQ6	T (LVDS)*	PL2A	7	VREF2_7	T (LVDS)*
E5	PL2B	7	VREF1_7/LDQ6	C (LVDS)*	PL2B	7	VREF1_7	C (LVDS)*
VCCIO	VCCIO7	-			GNDIO7	-		
GNDIO	GNDIO7	-			VCCIO	7		
E3	PL10A	7	LDQ14	T (LVDS)*	PL12A	7	LDQ16	T (LVDS)*
F3	PL10B	7	LDQ14	C (LVDS)*	PL12B	7	LDQ16	C (LVDS)*
F4	PL11A	7	LDQ14	T	PL13A	7	LDQ16	T
F5	PL11B	7	LDQ14	C	PL13B	7	LDQ16	C
E2	PL12A	7	LDQ14	T (LVDS)*	PL14A	7	LDQ16	T (LVDS)*
VCCIO	VCCIO7	7			VCCIO	7		
E1	PL12B	7	LDQ14	C (LVDS)*	PL14B	7	LDQ16	C (LVDS)*
G6	PL13A	7	LDQ14	T	PL15A	7	LDQ16	T
G7	PL13B	7	LDQ14	C	PL15B	7	LDQ16	C
H4	PL14A	7	LDQS14	T (LVDS)*	PL16A	7	LDQS16	T (LVDS)*
GNDIO	GNDIO7	-			GNDIO7	-		
H5	PL14B	7	LDQ14	C (LVDS)*	PL16B	7	LDQ16	C (LVDS)*
F1	PL15A	7	LDQ14	T	PL17A	7	LDQ16	T
F2	PL15B	7	LDQ14	C	PL17B	7	LDQ16	C
VCCIO	VCCIO7	7			VCCIO	7		
G3	PL16A	7	LDQ14	T (LVDS)*	PL18A	7	LDQ16	T (LVDS)*
G4	PL16B	7	LDQ14	C (LVDS)*	PL18B	7	LDQ16	C (LVDS)*
G1	PL17A	7	LDQ14	T	PL19A	7	LDQ16	T
G2	PL17B	7	LDQ14	C	PL19B	7	LDQ16	C
GNDIO	GNDIO7	-			GNDIO7	-		
-	-	-			VCCIO	7		
H6	NC	-			PL25A	7	LUM0_SPLLT_IN_A/LDQ24	T
-	-	-			VCCIO	7		
J6	NC	-			PL25B	7	LUM0_SPLLC_IN_A/LDQ24	C
H3	NC	-			PL26A	7	LUM0_SPLLT_FB_A/LDQ24	T
H2	NC	-			PL26B	7	LUM0_SPLLC_FB_A/LDQ24	C
-	-	-			GNDIO7	-		
-	-	-			VCCIO	7		
H1	PL18A	7	LDQ22		PL37A	7	LDQ41	
J4	PL19A	7	LDQ22	T	PL38A	7	LDQ41	T
J5	PL19B	7	LDQ22	C	PL38B	7	LDQ41	C
VCCIO	VCCIO7	7			VCCIO	7		
J2	PL20A	7	LDQ22	T (LVDS)*	PL39A	7	LDQ41	T (LVDS)*
J1	PL20B	7	LDQ22	C (LVDS)*	PL39B	7	LDQ41	C (LVDS)*
L6	PL21A	7	LDQ22	T	PL40A	7	LDQ41	T
L5	PL21B	7	LDQ22	C	PL40B	7	LDQ41	C
GNDIO	GNDIO7	-			GNDIO7	-		
K3	PL22A	7	LDQS22	T (LVDS)*	PL41A	7	LDQS41	T (LVDS)*
K4	PL22B	7	LDQ22	C (LVDS)*	PL41B	7	LDQ41	C (LVDS)*
K2	PL23A	7	LDQ22	T	PL42A	7	LDQ41	T
VCCIO	VCCIO7	7			VCCIO	7		

LFE2-50E/SE and LFE2-70E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-50E/SE					LFE2-70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
AE17	PB60B	4	BDQ60	C	PB69B	4	BDQ69	C
AB19	PB61A	4	BDQ60	T	PB70A	4	BDQ69	T
AE19	PB61B	4	BDQ60	C	PB70B	4	BDQ69	C
AF17	PB62A	4	BDQ60	T	PB71A	4	BDQ69	T
AE18	PB62B	4	BDQ60	C	PB71B	4	BDQ69	C
VCCIO	VCCIO4	4			VCCIO4	4		
W16	PB63A	4	BDQ60	T	PB72A	4	BDQ69	T
AA17	PB63B	4	BDQ60	C	PB72B	4	BDQ69	C
AF18	PB64A	4	BDQ60	T	PB73A	4	BDQ69	T
AF19	PB64B	4	BDQ60	C	PB73B	4	BDQ69	C
GND	GNDIO4	-			GNDIO4	-		
AA19	PB65A	4	BDQ69	T	PB74A	4	BDQ78	T
W17	PB65B	4	BDQ69	C	PB74B	4	BDQ78	C
Y19	PB66A	4	BDQ69	T	PB75A	4	BDQ78	T
Y17	PB66B	4	BDQ69	C	PB75B	4	BDQ78	C
AF20	PB67A	4	BDQ69	T	PB76A	4	BDQ78	T
VCCIO	VCCIO4	4			VCCIO4	4		
AE20	PB67B	4	BDQ69	C	PB76B	4	BDQ78	C
AA20	PB68A	4	BDQ69	T	PB77A	4	BDQ78	T
W18	PB68B	4	BDQ69	C	PB77B	4	BDQ78	C
AD20	PB69A	4	BDQS69	T	PB78A	4	BDQS78	T
GND	GNDIO4	-			GNDIO4	-		
AE21	PB69B	4	BDQ69	C	PB78B	4	BDQ78	C
AF21	PB70A	4	BDQ69	T	PB79A	4	BDQ78	T
AF22	PB70B	4	BDQ69	C	PB79B	4	BDQ78	C
VCCIO	VCCIO4	4			VCCIO4	4		
GND	GNDIO4	-			GNDIO4	-		
AE22	PB74A	4	BDQ78	T	PB92A	4	BDQ96	T
AD22	PB74B	4	BDQ78	C	PB92B	4	BDQ96	C
AF23	PB75A	4	BDQ78	T	PB93A	4	BDQ96	T
AE23	PB75B	4	BDQ78	C	PB93B	4	BDQ96	C
AD23	PB76A	4	BDQ78	T	PB94A	4	BDQ96	T
AC23	PB76B	4	BDQ78	C	PB94B	4	BDQ96	C
VCCIO	VCCIO4	4			VCCIO4	4		
AB20	PB77A	4	BDQ78	T	PB95A	4	BDQ96	T
AC20	PB77B	4	BDQ78	C	PB95B	4	BDQ96	C
GND	GNDIO4	-			GNDIO4	-		
AB21	PB78A	4	BDQS78	T	PB96A	4	BDQS96	T
AC22	PB78B	4	BDQ78	C	PB96B	4	BDQ96	C
W19	PB79A	4	BDQ78	T	PB97A	4	BDQ96	T
AA21	PB79B	4	BDQ78	C	PB97B	4	BDQ96	C
AF24	PB80A	4	BDQ78	T	PB98A	4	BDQ96	T
AE24	PB80B	4	BDQ78	C	PB98B	4	BDQ96	C
VCCIO	VCCIO4	4			VCCIO4	4		
Y20	PB81A	4	BDQ78	T	PB99A	4	BDQ96	T
AB22	PB81B	4	BDQ78	C	PB99B	4	BDQ96	C

LFE2-50E/SE and LFE2-70E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-50E/SE					LFE2-70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
G24	PR14B	2	RDQ16	C (LVDS)*	PR27B	2	RDQ29	C (LVDS)*
G23	PR14A	2	RDQ16	T (LVDS)*	PR27A	2	RDQ29	T (LVDS)*
VCCIO	VCCIO2	2			VCCIO2	2		
K19	PR13B	2	RDQ16	C	PR26B	2	RDQ29	C
J19	PR13A	2	RDQ16	T	PR26A	2	RDQ29	T
D26	PR12B	2	RDQ16	C (LVDS)*	PR25B	2	RDQ29	C (LVDS)*
C26	PR12A	2	RDQ16	T (LVDS)*	PR25A	2	RDQ29	T (LVDS)*
F22	PR11B	2	RDQ8	C	PR24B	2	RDQ21	C
E24	PR11A	2	RDQ8	T	PR24A	2	RDQ21	T
GND	GNDIO2	-			GNDIO2	-		
D25	PR10B	2	RDQ8	C (LVDS)*	PR23B	2	RDQ21	C (LVDS)*
C25	PR10A	2	RDQ8	T (LVDS)*	PR23A	2	RDQ21	T (LVDS)*
D24	PR9B	2	RDQ8	C	PR22B	2	RDQ21	C
B25	PR9A	2	RDQ8	T	PR22A	2	RDQ21	T
VCCIO	VCCIO2	2			VCCIO2	2		
H21	PR8B	2	RDQ8	C (LVDS)*	PR21B	2	RDQ21	C (LVDS)*
G22	PR8A	2	RDQS8	T (LVDS)*	PR21A	2	RDQS21	T (LVDS)*
B24	PR7B	2	RDQ8	C	PR20B	2	RDQ21	C
GND	GNDIO2	-			GNDIO2	-		
C24	PR7A	2	RDQ8	T	PR20A	2	RDQ21	T
D23	PR6B	2	RDQ8	C (LVDS)*	PR19B	2	RDQ21	C (LVDS)*
C23	PR6A	2	RDQ8	T (LVDS)*	PR19A	2	RDQ21	T (LVDS)*
G21	PR5B	2	RDQ8	C	PR18B	2	RDQ21	C
VCCIO	VCCIO2	2			VCCIO2	2		
H20	PR5A	2	RDQ8	T	PR18A	2	RDQ21	T
GND	GNDIO2	-			GNDIO2	-		
E22	PR2B	2	VREF2_2	C (LVDS)*	PR2B	2	VREF2_2	C (LVDS)*
F21	PR2A	2	VREF1_2	T (LVDS)*	PR2A	2	VREF1_2	T (LVDS)*
E23	PT82B	1	VREF2_1	C	PT100B	1	VREF2_1	C
GND	GNDIO1	-			GNDIO1	-		
D22	PT82A	1	VREF1_1	T	PT100A	1	VREF1_1	T
G20	PT81B	1		C	PT99B	1		C
J18	PT81A	1		T	PT99A	1		T
F20	PT80B	1		C	PT98B	1		C
VCCIO	VCCIO1	1			VCCIO1	1		
H19	PT80A	1		T	PT98A	1		T
A24	PT79B	1		C	PT97B	1		C
A23	PT79A	1		T	PT97A	1		T
E21	PT78B	1		C	PT96B	1		C
F19	PT78A	1		T	PT96A	1		T
C22	PT77B	1		C	PT95B	1		C
GND	GNDIO1	-			GNDIO1	-		
E20	PT77A	1		T	PT95A	1		T
B22	PT76B	1		C	PT94B	1		C
VCCIO	VCCIO1	1			VCCIO1	1		
B23	PT76A	1		T	PT94A	1		T

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
AD2	PL90B	6	LDQ88	C (LVDS)*
AD7	PL91A	6	LDQ88	T
GND	GNDIO6	-		
AB9	PL91B	6	LDQ88	C
AD5	TCK	-		
AE7	TDI	-		
AD4	TMS	-		
AA9	TDO	-		
AD3	VCCJ	-		
AC8	PB2A	5	VREF2_5/BDQ6	T
AE8	PB2B	5	VREF1_5/BDQ6	C
AD8	PB3A	5	BDQ6	T
AF8	PB3B	5	BDQ6	C
AG7	PB4A	5	BDQ6	T
VCCIO	VCCIO5	5		
AH7	PB4B	5	BDQ6	C
AC9	PB5A	5	BDQ6	T
AE9	PB5B	5	BDQ6	C
AD9	PB6A	5	BDQS6	T
GND	GNDIO5	-		
AF9	PB6B	5	BDQ6	C
AB10	PB7A	5	BDQ6	T
AA10	PB7B	5	BDQ6	C
AJ7	PB8A	5	BDQ6	T
VCCIO	VCCIO5	5		
AK7	PB8B	5	BDQ6	C
AC10	PB9A	5	BDQ6	T
AE10	PB9B	5	BDQ6	C
AJ8	PB10A	5	BDQ6	T
GND	GNDIO5	-		
AK8	PB10B	5	BDQ6	C
AF6	PB11A	5	BDQ15	T
AF7	PB11B	5	BDQ15	C
AG5	PB12A	5	BDQ15	T
AH5	PB12B	5	BDQ15	C
AG6	PB13A	5	BDQ15	T
AH6	PB13B	5	BDQ15	C
VCCIO	VCCIO5	5		
AJ4	PB14A	5	BDQ15	T
AK4	PB14B	5	BDQ15	C
GND	GNDIO5	-		
AJ5	PB15A	5	BDQS15	T
AK5	PB15B	5	BDQ15	C

LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M50E/SE					LFE2M70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
L13	VCC	-			VCC	-		
L18	VCC	-			VCC	-		
L19	VCC	-			VCC	-		
M11	VCC	-			VCC	-		
M12	VCC	-			VCC	-		
M13	VCC	-			VCC	-		
M14	VCC	-			VCC	-		
M15	VCC	-			VCC	-		
M16	VCC	-			VCC	-		
M17	VCC	-			VCC	-		
M18	VCC	-			VCC	-		
M19	VCC	-			VCC	-		
M20	VCC	-			VCC	-		
N11	VCC	-			VCC	-		
N12	VCC	-			VCC	-		
N19	VCC	-			VCC	-		
N20	VCC	-			VCC	-		
P12	VCC	-			VCC	-		
P19	VCC	-			VCC	-		
R12	VCC	-			VCC	-		
R19	VCC	-			VCC	-		
T12	VCC	-			VCC	-		
T19	VCC	-			VCC	-		
U12	VCC	-			VCC	-		
U19	VCC	-			VCC	-		
V11	VCC	-			VCC	-		
V12	VCC	-			VCC	-		
V19	VCC	-			VCC	-		
V20	VCC	-			VCC	-		
W11	VCC	-			VCC	-		
W12	VCC	-			VCC	-		
W13	VCC	-			VCC	-		
W14	VCC	-			VCC	-		
W15	VCC	-			VCC	-		
W16	VCC	-			VCC	-		
W17	VCC	-			VCC	-		
W18	VCC	-			VCC	-		
W19	VCC	-			VCC	-		
W20	VCC	-			VCC	-		
Y12	VCC	-			VCC	-		
Y13	VCC	-			VCC	-		
Y18	VCC	-			VCC	-		
Y19	VCC	-			VCC	-		
D14	VCCIO0	0			VCCIO0	0		
E6	VCCIO0	0			VCCIO0	0		
E9	VCCIO0	0			VCCIO0	0		
F12	VCCIO0	0			VCCIO0	0		
K12	VCCIO0	0			VCCIO0	0		

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
AJ2	LLC_SQ_HDINN3	14		C
AH4	LLC_SQ_VCCTX3	14		
AK5	LLC_SQ_HDOUTP3	14		T
AK4	LLC_SQ_VCCOB3	14		
AJ5	LLC_SQ_HDOUTN3	14		C
AH5	LLC_SQ_VCCTX2	14		
AJ6	LLC_SQ_HDOUTN2	14		C
AH6	LLC_SQ_VCCOB2	14		
AK6	LLC_SQ_HDOUTP2	14		T
AH2	LLC_SQ_VCCRX2	14		
AJ3	LLC_SQ_HDINN2	14		C
AH3	LLC_SQ_VCCIB2	14		
AK3	LLC_SQ_HDINP2	14		T
AH7	LLC_SQ_VCCP	14		
AG7	LLC_SQ_REFCLKP	14		T
AF7	LLC_SQ_REFCLKN	14		C
AJ7	LLC_SQ_VCCAUX33	14		
AK11	LLC_SQ_HDINP1	14		T
AH11	LLC_SQ_VCCIB1	14		
AJ11	LLC_SQ_HDINN1	14		C
AH12	LLC_SQ_VCCRX1	14		
AK8	LLC_SQ_HDOUTP1	14		T
AH8	LLC_SQ_VCCOB1	14		
AJ8	LLC_SQ_HDOUTN1	14		C
AH9	LLC_SQ_VCCTX1	14		
AJ9	LLC_SQ_HDOUTN0	14		C
AK10	LLC_SQ_VCCOB0	14		
AK9	LLC_SQ_HDOUTP0	14		T
AH10	LLC_SQ_VCCTX0	14		
AJ12	LLC_SQ_HDINN0	14		C
AJ13	LLC_SQ_VCCIB0	14		
AK12	LLC_SQ_HDINP0	14		T
AH13	LLC_SQ_VCCRX0	14		
AF10	PB30A	5	BDQ33	T
AE8	PB30B	5	BDQ33	C
AE11	PB31A	5	BDQ33	T
VCCIO	VCCIO5	5		
AD9	PB31B	5	BDQ33	C
AE10	PB32A	5	BDQ33	T
AD10	PB32B	5	BDQ33	C
AE13	PB33A	5	BDQS33	T
GNDIO	GNDIO5	-		
AC12	PB33B	5	BDQ33	C

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
D19	PT93B	1		C
E18	PT93A	1		T
D18	PT92B	1		C
C17	PT92A	1		T
A17	PT91B	1		C
B17	PT91A	1		T
GNDIO	GNDIO1	-		
VCCIO	VCCIO1	1		
J18	PT75B	1		C
J19	PT75A	1		T
H17	PT74B	1		C
J17	PT74A	1		T
F18	PT73B	1		C
F17	PT73A	1		T
GNDIO	GNDIO1	-		
A16	PT72B	1		C
B16	PT72A	1		T
G17	PT71B	1		C
G16	PT71A	1		T
VCCIO	VCCIO1	1		
H16	PT70B	1		C
F16	PT70A	1		T
J16	PT69B	1		C
G15	PT69A	1		T
GNDIO	GNDIO1	-		
C16	PT68B	1		C
D16	PT68A	1		T
J15	PT67B	1		C
H15	PT67A	1		T
VCCIO	VCCIO1	1		
A15	PT66B	1	VREF2_1	C
B15	PT66A	1	VREF1_1	T
F15	PT65B	1	PCLKC1_0	C
E16	PT65A	1	PCLKT1_0	T
C15	PT64B	0	PCLKC0_0	C
GNDIO	GNDIO0	-		
D15	PT64A	0	PCLKT0_0	T
C14	PT63B	0	VREF2_0	C
E15	PT63A	0	VREF1_0	T
G14	PT62B	0		C
VCCIO	VCCIO0	0		
J14	PT62A	0		T
F14	PT61B	0		C

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
M23	GND	-		
M8	GND	-		
N14	GND	-		
N15	GND	-		
N16	GND	-		
N17	GND	-		
N27	GND	-		
N4	GND	-		
P11	GND	-		
P13	GND	-		
P14	GND	-		
P15	GND	-		
P16	GND	-		
P17	GND	-		
P18	GND	-		
P20	GND	-		
R10	GND	-		
R11	GND	-		
R13	GND	-		
R14	GND	-		
R15	GND	-		
R16	GND	-		
R17	GND	-		
R18	GND	-		
R20	GND	-		
R21	GND	-		
R24	GND	-		
R7	GND	-		
T10	GND	-		
T11	GND	-		
T13	GND	-		
T14	GND	-		
T15	GND	-		
T16	GND	-		
T17	GND	-		
T18	GND	-		
T20	GND	-		
T21	GND	-		
T24	GND	-		
T7	GND	-		
U11	GND	-		
U13	GND	-		
U14	GND	-		

LFE2M70E/SE and LFE2M100E/SE Logic Signal Connections: 1152 fpBGA (Cont.)

LFE2M70E/SE				LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
AF27	RLM0_PLLCAP	3			RLM0_PLLCAP	3		
AF28	PR85B	3	RLM0_GDLLC_FB_A	C	PR102B	3	RLM0_GDLLC_FB_A/RDQ99	C
GNDIO	GNDIO3	-			GNDIO3	-		
AD26	PR85A	3	RLM0_GDLLT_FB_A	T	PR102A	3	RLM0_GDLLT_FB_A/RDQ99	T
AJ32	PR84B	3	RLM0_GDLLC_IN_A**	C (LVDS)*	PR101B	3	RLM0_GDLLC_IN_A**/ RDQ99	C (LVDS)*
AJ33	PR84A	3	RLM0_GDLLT_IN_A**	T (LVDS)*	PR101A	3	RLM0_GDLLT_IN_A**/ RDQ99	T (LVDS)*
AJ34	PR83B	3	RLM0_GPLLC_IN_A**	C	PR100B	3	RLM0_GPLLC_IN_A**/ RDQ99	C
VCCIO	VCCIO3	3			VCCIO3	3		
AK34	PR83A	3	RLM0_GPLLT_IN_A**	T	PR100A	3	RLM0_GPLLT_IN_A**/ RDQ99	T
AH33	PR82B	3	RLM0_GPLLC_FB_A	C (LVDS)*	PR99B	3	RLM0_GPLLC_FB_A/RDQ99	C (LVDS)*
AH34	PR82A	3	RLM0_GPLLT_FB_A/RDQS82****	T (LVDS)*	PR99A	3	RLM0_GPLLT_FB_A/ RDQS99	T (LVDS)*
GNDIO	GNDIO3	-			GNDIO3	-		
AF29	PR81B	3	RDQ82	C	PR98B	3	RDQ99	C
AF31	PR81A	3	RDQ82	T	PR98A	3	RDQ99	T
AG33	PR80B	3	RDQ82	C (LVDS)*	PR97B	3	RDQ99	C (LVDS)*
AG34	PR80A	3	RDQ82	T (LVDS)*	PR97A	3	RDQ99	T (LVDS)*
VCCIO	VCCIO3	3			VCCIO3	3		
AF30	PR79B	3	RDQ82	C	PR96B	3	RDQ99	C
AF32	PR79A	3	RDQ82	T	PR96A	3	RDQ99	T
AE29	PR78B	3	RDQ82	C (LVDS)*	PR95B	3	RDQ99	C (LVDS)*
AE30	PR78A	3	RDQ82	T (LVDS)*	PR95A	3	RDQ99	T (LVDS)*
AF33	NC	-			PR93B	3	RDQ90	C
AF34	NC	-			PR93A	3	RDQ90	T
-	-	-			GNDIO3	-		
AC27	NC	-			PR92B	3	RDQ90	C (LVDS)*
AC28	NC	-			PR92A	3	RDQ90	T (LVDS)*
AD29	NC	-			PR91B	3	RDQ90	C
AD30	NC	-			PR91A	3	RDQ90	T
-	-	-			VCCIO3	3		
AE33	NC	-			PR90B	3	RDQ90	C (LVDS)*
AE34	NC	-			PR90A	3	RDQS90	T (LVDS)*
AD32	NC	-			PR89B	3	RDQ90	C
-	-	-			GNDIO3	-		
AD31	NC	-			PR89A	3	RDQ90	T
AB25	NC	-			PR88B	3	RDQ90	C (LVDS)*
AC25	NC	-			PR88A	3	RDQ90	T (LVDS)*
AB28	NC	-			PR87B	3	RDQ90	C
-	-	-			VCCIO3	3		
AA26	NC	-			PR87A	3	RDQ90	T
AD33	NC	-			PR86B	3	RDQ90	C (LVDS)*
AD34	NC	-			PR86A	3	RDQ90	T (LVDS)*
AC29	PR76B	3	RDQ73	C	PR84B	3	RDQ81	C
GNDIO	GNDIO3	-			GNDIO3	-		
AA27	PR76A	3	RDQ73	T	PR84A	3	RDQ81	T
AC32	PR75B	3	RDQ73	C (LVDS)*	PR83B	3	RDQ81	C (LVDS)*
AC31	PR75A	3	RDQ73	T (LVDS)*	PR83A	3	RDQ81	T (LVDS)*

LFE2M70E/SE and LFE2M100E/SE Logic Signal Connections: 1152 fpBGA (Cont.)

LFE2M70E/SE				LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
E5	ULC_SQ_REFCLKN	11		C	ULC_SQ_REFCLKN	11		C
D5	ULC_SQ_REFCLKP	11		T	ULC_SQ_REFCLKP	11		T
D6	ULC_SQ_VCCP	11			ULC_SQ_VCCP	11		
C5	ULC_SQ_HDINP2	11		T	ULC_SQ_HDINP2	11		T
D4	ULC_SQ_VCCIB2	11			ULC_SQ_VCCIB2	11		
C4	ULC_SQ_HDINN2	11		C	ULC_SQ_HDINN2	11		C
B5	ULC_SQ_VCCRX2	11			ULC_SQ_VCCRX2	11		
A5	ULC_SQ_HDOUTP2	11		T	ULC_SQ_HDOUTP2	11		T
D3	ULC_SQ_VCCOB2	11			ULC_SQ_VCCOB2	11		
A4	ULC_SQ_HDOUTN2	11		C	ULC_SQ_HDOUTN2	11		C
B4	ULC_SQ_VCCTX2	11			ULC_SQ_VCCTX2	11		
A3	ULC_SQ_HDOUTN3	11		C	ULC_SQ_HDOUTN3	11		C
C1	ULC_SQ_VCCOB3	11			ULC_SQ_VCCOB3	11		
A2	ULC_SQ_HDOUTP3	11		T	ULC_SQ_HDOUTP3	11		T
B3	ULC_SQ_VCCTX3	11			ULC_SQ_VCCTX3	11		
C3	ULC_SQ_HDINN3	11		C	ULC_SQ_HDINN3	11		C
B1	ULC_SQ_VCCIB3	11			ULC_SQ_VCCIB3	11		
C2	ULC_SQ_HDINP3	11		T	ULC_SQ_HDINP3	11		T
B2	ULC_SQ_VCCRX3	11			ULC_SQ_VCCRX3	11		
AA13	VCC	-			VCC	-		
AA14	VCC	-			VCC	-		
AA15	VCC	-			VCC	-		
AA16	VCC	-			VCC	-		
AA17	VCC	-			VCC	-		
AA18	VCC	-			VCC	-		
AA19	VCC	-			VCC	-		
AA20	VCC	-			VCC	-		
AA21	VCC	-			VCC	-		
AA22	VCC	-			VCC	-		
AB14	VCC	-			VCC	-		
AB15	VCC	-			VCC	-		
AB20	VCC	-			VCC	-		
AB21	VCC	-			VCC	-		
N14	VCC	-			VCC	-		
N15	VCC	-			VCC	-		
N20	VCC	-			VCC	-		
N21	VCC	-			VCC	-		
P13	VCC	-			VCC	-		
P14	VCC	-			VCC	-		
P15	VCC	-			VCC	-		
P16	VCC	-			VCC	-		
P17	VCC	-			VCC	-		
P18	VCC	-			VCC	-		
P19	VCC	-			VCC	-		
P20	VCC	-			VCC	-		
P21	VCC	-			VCC	-		
P22	VCC	-			VCC	-		
R13	VCC	-			VCC	-		
R14	VCC	-			VCC	-		

Date	Version	Section	Change Summary
August 2007 (cont.)	02.8 (cont.)	DC and Switching (cont.)	sysCLOCK GPLL timing has been updated.
		Pinout Information	Added ECP2M50 (484/672/900-fpBGA), ECP2M70 (900-fpBGA) and ECP2M100 (900-fpBGA) pinout information.
		Ordering Information	1156-fpBGA package option has been removed from the LatticeECP2M family.
September 2007	02.9	Pinout Information	Added Thermal Management text section.
February 2008	03.0	Architecture	Added LVCMOS33D description.
		DC and Switching	LatticeECP2M Supply Current has been updated.
			Typical Building Block Function Performance, External Switching Characteristics, Internal Switching Characteristics, Family Timing Adders, sysCLOCK GPLL Timing, sysCLOCK SPLL Timing, DLL Timing and sysCONFIG Port Timing Specifications have been updated (timing rev. A 0.11).
			Figure 3-9. Read/Write Mode (Normal) and Figure 3-10. Read/Write Mode with Input and Output Registers have been updated.
			Table 3-8. Channel output Jitter (Max) has been updated.
		Pinout Information	Signal description has been updated.
			Added 1152-fpBGA pinouts for the ECP2M70 and ECP2M100.
April 2008	03.1	Pinout Information	Available DDR Interfaces per I/O Bank for the LFE2M35 (484/672-fpBGA) have been updated.
June 2008	03.2	Introduction	Family Selection Guide table - Updated number of EBR SRAM Blocks for the ECP2-70 device.
		Architecture	Removed Read-Before-Write sysMEM EBR mode.
			Clarification of the operation of the secondary clock regions.
		DC and Switching Characteristics	Removed Read-Before-Write sysMEM EBR mode.
August 2008	03.3	Architecture	Clarification of the operation of the secondary clock regions.
		Pinout Information	Added information for [LOC]DQ[num] to Signal Descriptions table.
January 2009	03.4	DC and Switching Characteristics	Updated typical and max. jitter numbers in Channel Output Jitter table for x10 mode.
			Added Channel Output Jitter table for x20 mode.
November 2009	03.5	DC and Switching Characteristics	Updated SPI/SPIm Configuration Waveforms diagram.
			Updated footnotes in LatticeECP2 Initialization Supply Current table.
			Updated footnotes in LatticeECP2M Initialization Supply Current table.
			Updated footnotes in SERDES High Speed Data Receiver (LatticeECP2M Family Only) table.
			Updated max. value for t_{DINIT} parameter in LatticeECP2/M sysCONFIG Port Timing Specifications table.
			Updated Serial Output Timing and Levels table.
			Updated Figure 3-5 MLVDS
			Updated Table 3-7 Serial Output Timing and Levels
			Updated Table 3-15 Power Down/Power Up Specification
		Pinout Information	Signal Descriptions table - corrected references to ULM, URM, LRM (changed to LUM, RUM and RLM), added footnote 5.